BOARD LEVEL COOLING - 3375

3375 is a series of board level heat sinks designed to cool BGA and FPGA devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
335714B00000G	BGA, FPGA
335714B00032G	BGA, FPGA

HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Tape
Thermal Interface Material 335714B00000G	-
Thermal Interface Material 335714B00032G	T405R Chomerics Tape for Metal Surfaces

Property	Details
Heat Sink Width (mm)	30.15
Heat Sink Length (mm)	30.15
Heat Sink Height (mm)	6.60
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown as: in. (mm)